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Trusted Electronic Designer, Fabricator and Assembler Requirements

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Association Connecting Electronics Industries



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- Show relationship to Design for Manufacturability (DFM) and Design for the Environment (DFE)
- Minimize time to market
- Contain simple (simplified) language
- Just include spec information
- Focus on end product performance
- Include a feedback system on use and problems for future improvement

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- Increase time-to-market
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Trusted Electronic Designer, Fabricator and Assembler Requirements

Developed by the Trusted Supplier Task Group (2-19b) of the Electronic Product Data Description Committee (2-10) of IPC

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Users of this publication are encouraged to participate in the development of future revisions.

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Trusted Electronic Designer, Fabricator and Assembler Requirements

1 SCOPE

This standard provides minimum requirements, policies and procedures for printed board design, fabrication and assembly organizations and/or companies to become trusted sources for markets requiring high levels of confidence in the integrity of delivered products. These trusted sources **shall** ensure quality, supply chain risk management (SCRM), security and chain of custody (ChoC).

Trusted source certification of non-U.S. printed board design, fabrication and assembly organizations requires a sponsor and are required to meet the requirements in Appendix D, in lieu of section 3.3 and Appendix B.

Demonstration of the ability to meet and maintain the requirements of this standard as trusted design, fabrication or assembly organization benefits customers that provide end-products for markets desiring a high level of integrity assurance (e.g., commercial, industrial, military, aerospace, automotive and medical).

In the context of this standard, the terms trust and trusted are used to reflect a commitment to delivered product and process integrity assurance by printed board designers, fabricators and assemblers. The user should not confuse this certification with defense-microelectronics-specific “Trusted Supplier” accreditation administered by the Defense Microelectronics Activity (DMEA) Trusted Access Program Office. IPC-1791 certification does not include U.S. Department of Defense (DoD) facility clearance unless compelled by customer-specific requirements and pursued independent of this standard.

1.1 Purpose and Background

1.1.1 Source Technology and Capability Design, fabrication and assembly organizations have different levels of capability in terms of technology, materials, product complexity, capacity and lead times. This standard assumes the customer has certified the capability of their chosen supplier.

1.1.2 Interpretation of Requirements for the Purposes of this Standard This standard covers requirements for quality, SCRM, security and ChoC:

- Quality and performance requirements (e.g., IPC-2000 series, IPC-6000 series, IPC-A-600, IPC-A-610, MIL-PRF-31032, AS9100, National Aerospace and Defense Contractors Accreditation Program (Nadcap), etc.) **shall** be as defined in this standard for the type of organization.
- Requirements for SCRM **shall** be as defined in this standard for the type of organization.
- Security requirements **shall** be the same for all types of organizations.
- The requirements for ChoC **shall** be the same for all types of organizations.

1.1.3 Benefits of Using Organizations Certified to this Standard By using designers, printed board fabricators and printed board assemblers that have been certified to this standard, customers will be assured that their supplier(s):

- Maintains a quality system
- Maintains a SCRM system to ensure any threats related to disruption in supply are understood and managed
- Manages a security system to protect products and services from unauthorized access, particularly in support of export control
- Provides an ensured ChoC system for electronic and physical materials

1.1.4 Additional Detail See Appendix A for additional explanatory material.

1.2 Classification IPC standards recognize that electrical and electronic assemblies are subject to classifications by intended end-item use. Three general end-product classes have been established to reflect differences in manufacturability, complexity, functional performance requirements, and verification (inspection/test) frequency. It should be recognized that there may be overlaps of equipment between classes.

CLASS 1 General Electronic Products

Includes products suitable for applications where the major requirement is function of the completed assembly.

CLASS 2 Dedicated Service Electronic Products

Includes products where continued performance and extended life is required, and for which uninterrupted service is desired but not critical. Typically, the end-use environment would not cause failures.

CLASS 3 High Performance/Harsh Environment Electronic Products

Includes products where continued high performance or performance-on-demand is critical, equipment downtime cannot be tolerated, end-use environment may be uncommonly harsh, and the equipment must function when required, such as life support or other critical systems.

1.3 Definition of Requirements The words **shall** or **shall not** are used in the text of this document wherever there is a requirement for materials, preparation, process control or acceptance.

The word “should” reflects recommendations and is used to reflect general industry practices and procedures for guidance only.

The word “will” is used to express a declaration of purpose.

Line drawings and illustrations are depicted herein to assist in the interpretation of the written requirements of this Standard. The text takes precedence over the figures.

1.4 Certification To ensure cost-effective use of trusted suppliers, this standard provides three types of certification (see 1.4.1 through 1.4.3). Certification types are based on the function of the organization. All types **shall** meet the requirements of 1.4.4 through 1.4.6.

1.4.1 Type 1 – Printed Board Design Organizations The organization responsible for the printed board and printed board assembly design. Typically, the design is composed of a variety of files in various formats used as outputs of the design process. The designs function as inputs to the printed board and assembly manufacturing process.

1.4.2 Type 2 – Printed Board Fabrication Organizations The organization responsible for the manufacture of the printed board.

1.4.3 Type 3 – Printed Board Assembly Organizations The organization responsible for assembly processes and verification operations necessary to ensure full compliance of assemblies.

1.4.4 Length of Certification The length of certification is three years. A certified company **shall** submit to IPC Validation Services (<https://ipcvalidation.org/>) a copy of its ITAR renewal annually and update any changes in organizational structure that affect the administration of ITAR.

1.4.5 Ownership Changes During the three-year certification period, any changes in foreign investor or ownership **shall** be voluntarily notified to the Committee on Foreign Investment in the United States (CFIUS). Instructions for the voluntary notice are given in the CFIUS website (www.treasury.gov). The organization **shall** also notify IPC Validation Services within 30 days of the filing. Ownership changes **shall** have export control compliance. The foreign investor or owner **shall not** be on the ITAR prohibited country list (www.ecfr.gov).

1.4.6 Management Changes During the three-year certification period, any changes to management, organizational structure, certifications or processes **shall** be reported to IPC Validation Services within 30 days of the change. Changes resulting in noncompliance to any of the requirements in this standard **shall** result in termination of the certification to this standard.

1.5 Abbreviations and Acronyms See Appendix E for full spellings of abbreviations (including elements) and acronyms used in this standard.

1.6 Terms and Definitions Terms and definitions **shall** be in accordance with IPC-T-50 and 1.6.1 through 1.6.32.